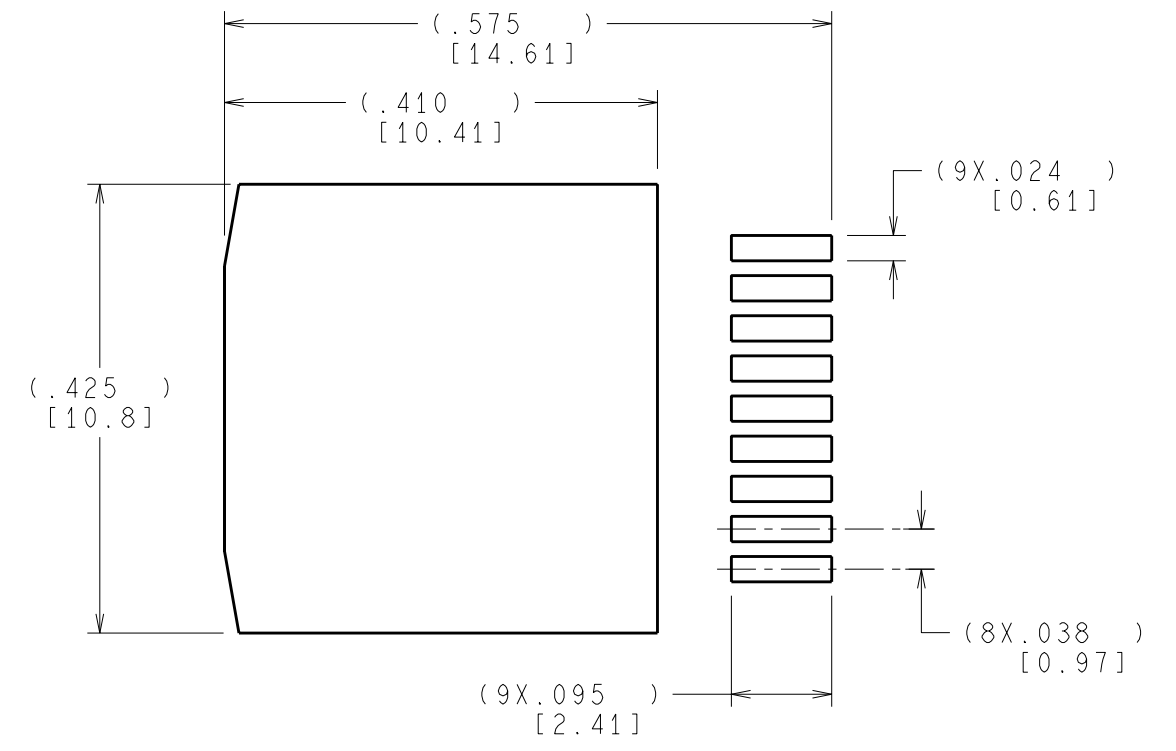
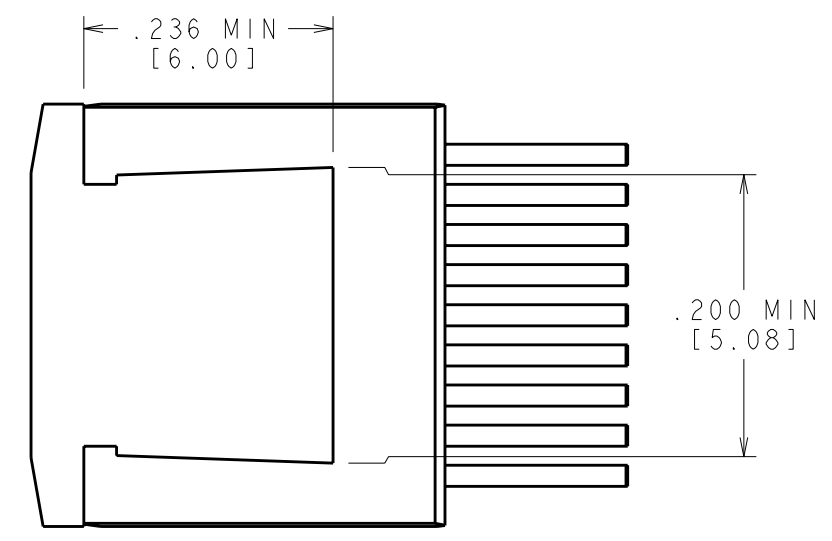
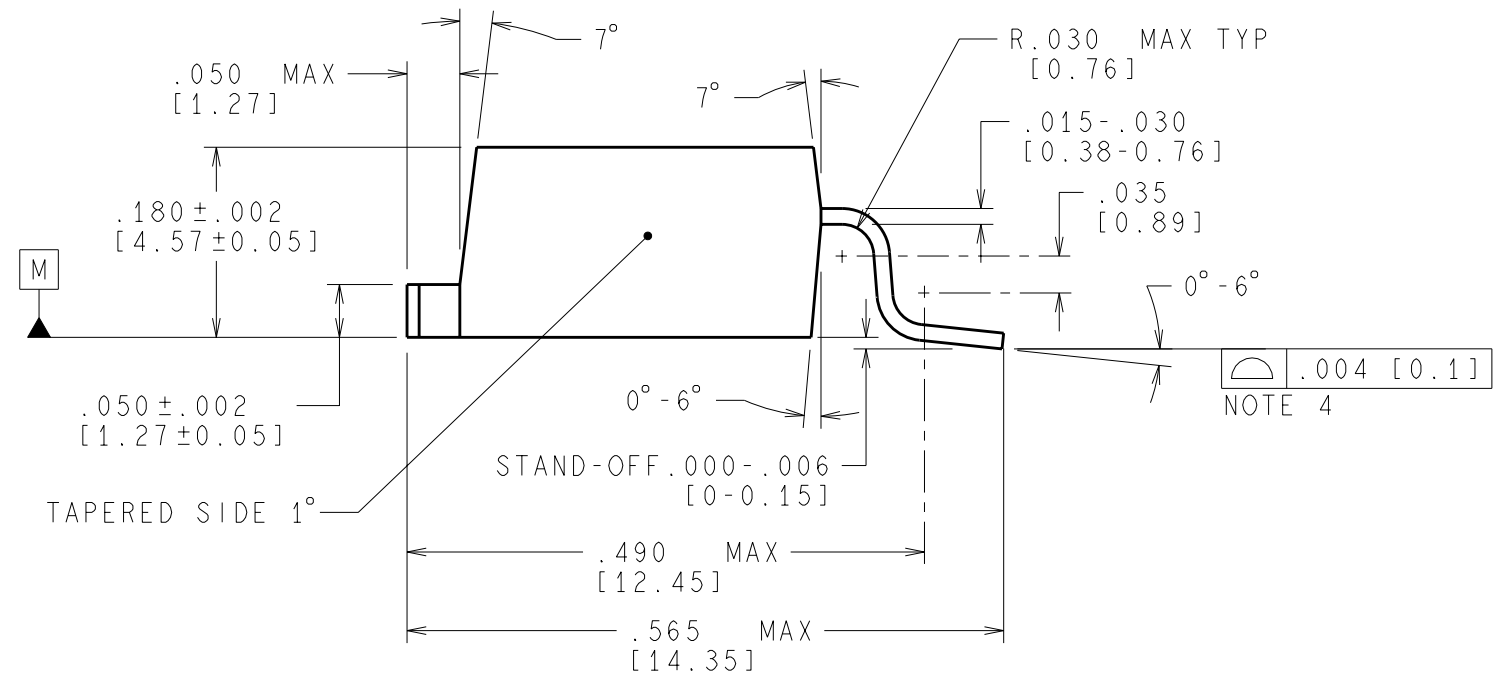
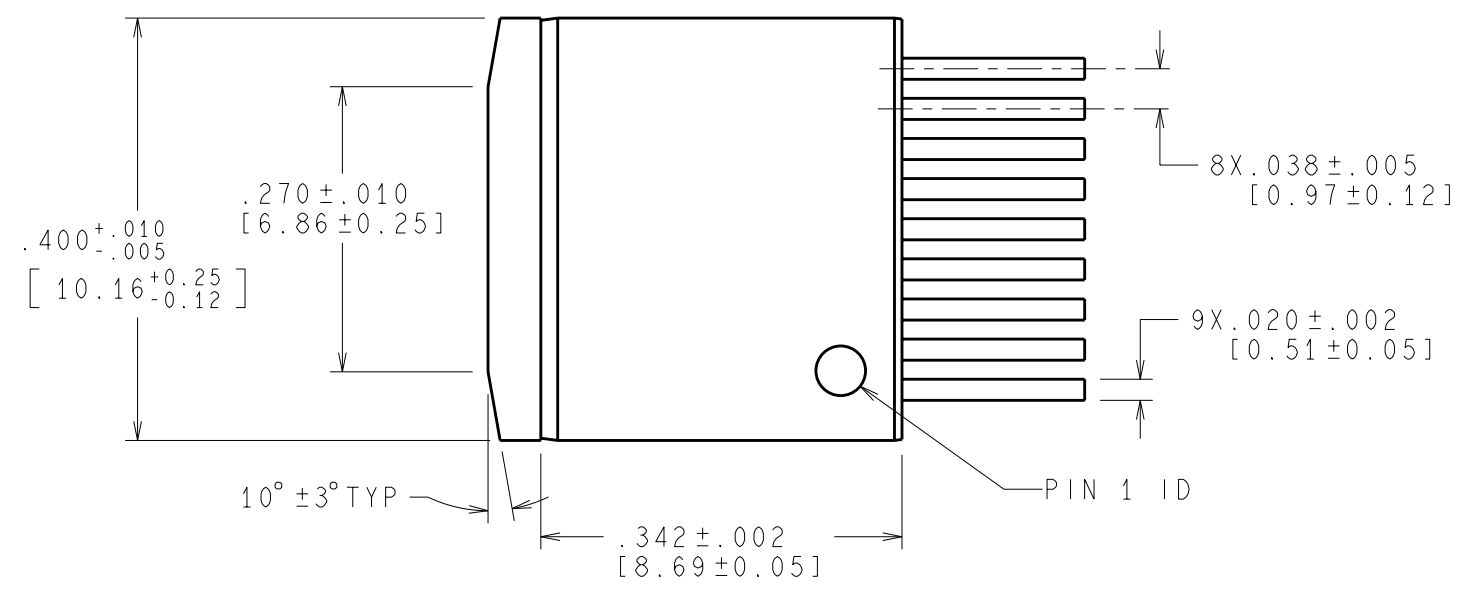


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10590	09/06/1994	TL/JF
B	DIM .236[6.00] WAS .250[6.35]; REFORMAT DWG TO B SIZE; UPDATE NOTE 5	1694	12/17/2004	TL/AS



RECOMMENDED LAND PATTERN

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH:
200 MICROMETERS / 5.08 MICROMETERS MINIMUM LEAD/TIN
15/85 ON OLIN 194 COPPER OR EQUIVALENT.
 - MAXIMUM VERTICAL BURR ON HEATSINK NOT TO EXCEED
.003 IN/ 0.05 mm.
 - NO PACKAGE CHIPS, CRACKS OR SURFACE INDENTATION ALLOWED
AFTER FORMING.
 - UNDER ALL CONDITIONS, LEAD(S) MUST NOT BE ABOVE DATUM -M-
AND NO LEADS MAY BE LOWER THAN .006 IN/ 0.15 mm MEASURED FROM
DATUM -M- TO THE BOTTOM OF THE LEADS.
 - NO JEDEC REGISTRATION AS OF DECEMBER 2004.

CONTROLLING DIMENSION: INCH
DIMENSIONS IN [] ARE MILLIMETERS

APPROVALS	DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	TO-263, MOLDED, 9 LEAD, SURFACE MOUNT
DRAWN F. LEQUANG	09/06/1994		
DFTG. CHK. MARTA SUCHY	12/17/2004		
ENGR. CHK. ASNOR SULAIMAN	12/17/2004		
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	NTS	B	(SC)MKT-TS9A
	FORMERLY: N/A		REV B